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16/Amend C
3-18-03
C. Moore

IN THE UNITED STATES PATENT & TRADEMARK OFFICE

IN RE APPLICATION OF: :
TATSUYA KUNIKIYO : GROUP ART UNIT: 2814
SERIAL NO: 09/612,298 :
RCE FILED: NOVEMBER 1, 2002 : EXAMINER: CAO, P.
FOR: SEMICONDUCTOR DEVICE HAVING
MULTILAYER INTERCONNECTION
STRUCTURE

AMENDMENT

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON, D.C. 20231

SIR:

In response to the Office Action dated December 18, 2002, please amend this
application as follows:

IN THE CLAIMS

Please amend Claim 1 as shown in clean form below. A marked-up copy of the
amended claim is attached.

C1

1. (Twice Amended) A semiconductor device comprising:
a semiconductor substrate having a main surface along which a semiconductor
element is formed;
interlayer insulating films formed on said main surface;
conductive interconnections provided in a plurality of layers separated by said
interlayer insulating films;

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